

AMENDMENTS TO THE SPECIFICATION

In the Specification:

Please replace Paragraph 0018 of the substitute specification with the following paragraph:

Furthermore, the printing plate can also be engraved directly with the ~~embossed~~ embossing microstructures lowered relative to the unengraved printing plate level. However, this presupposes the use of a precision engraving apparatus since standard devices for engraving intaglio printing plates do not have sufficient precision for reproducibly producing given structures whose dimensions are smaller than 100 microns. Precision engraving can be done both by mechanical, i.e. chip-removing, engraving and by laser engraving.

Please replace Paragraph 0022 of the substitute specification with the following paragraph:

Due to the very high contact pressure in intaglio printing, the substrate material, for example cotton paper, is compacted and permanently compressed even in the unprinted or unembossed areas. Lowering of the ~~embossed~~ embossing structures in the printing plate causes an uncompressed, or at least less compressed, area in the corresponding area of the machined substrate, with the ~~embossed~~ embossing microstructures rising therefrom. As wearing protection, the ~~embossed~~ embossing microstructures can be provided with stabilizing protective layers.